

2  AREA OF INNER SMT LAND REQUIRES PATTERN PROHIBITION OR RESIST TREATMENT TO PREVENT THE PATTERN TOUCHING TO THE CONTACTS.

3 () INDICATES A REFERENCE DIMENSION.

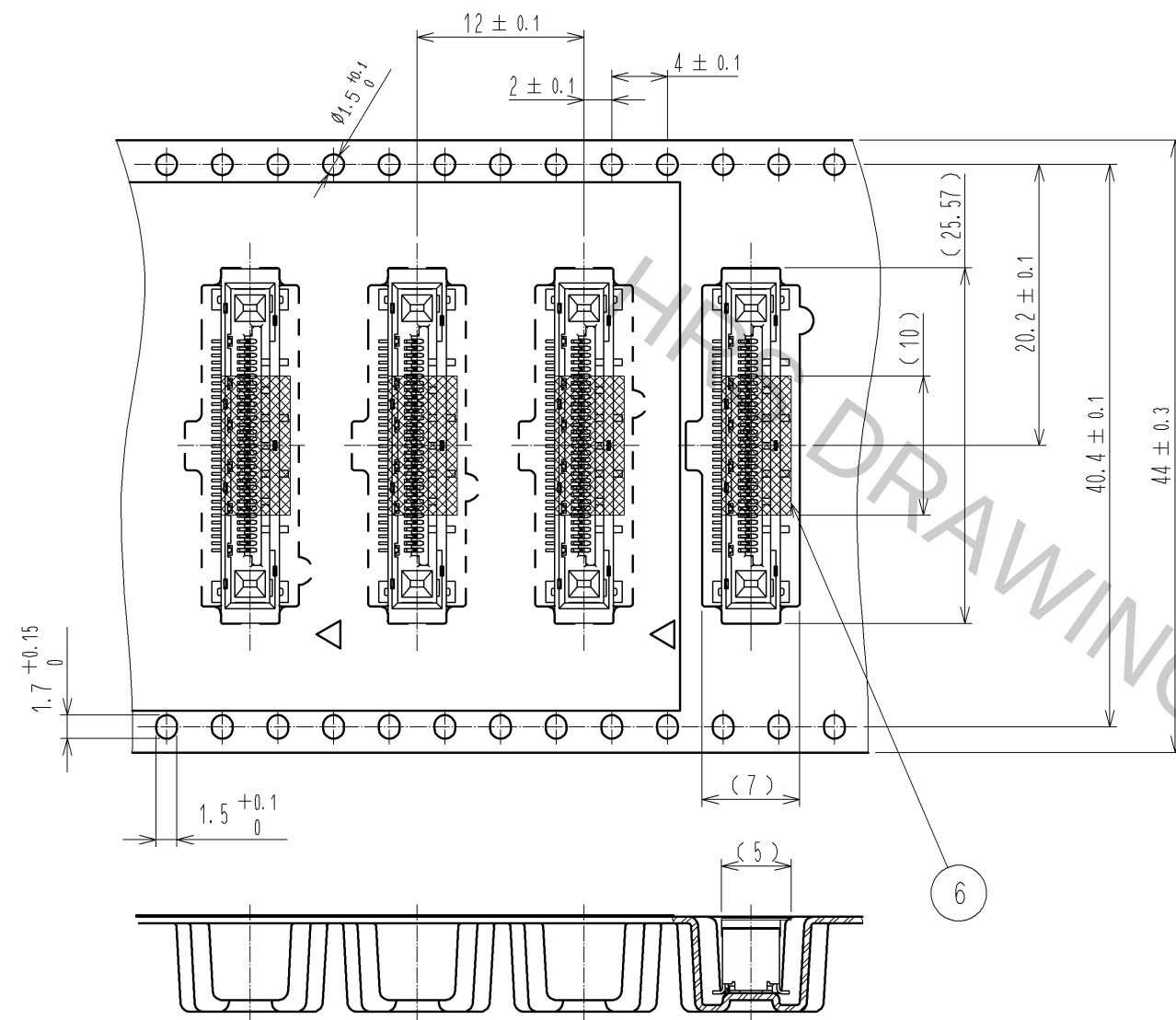
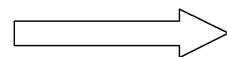
4 MANUFACTURING PROCESS COULD LEAVE SCRATCH AND/OR PUNCH MARKS HAVING NO AFFECT ON THE PRODUCT PERFORMANCE.

5 PACKAGING FOR THIS PRODUCT APPLIES EMBOSSED CARRIER TAPE PACKAGING. SEE SHEET 2/2 FOR DETAILS.

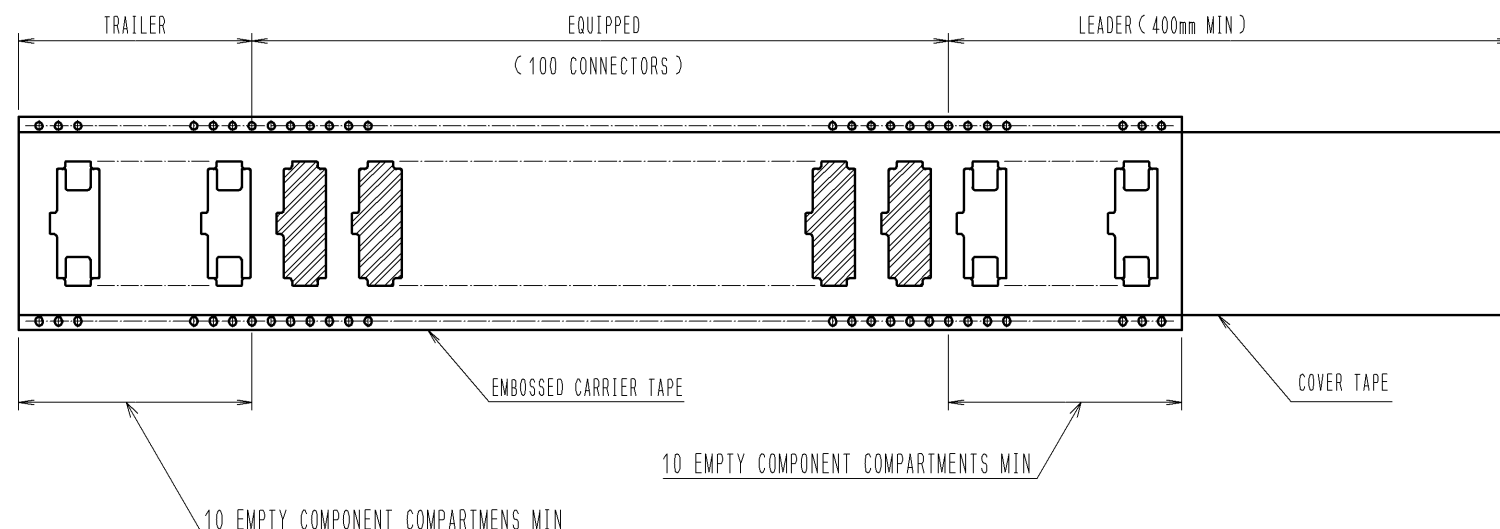
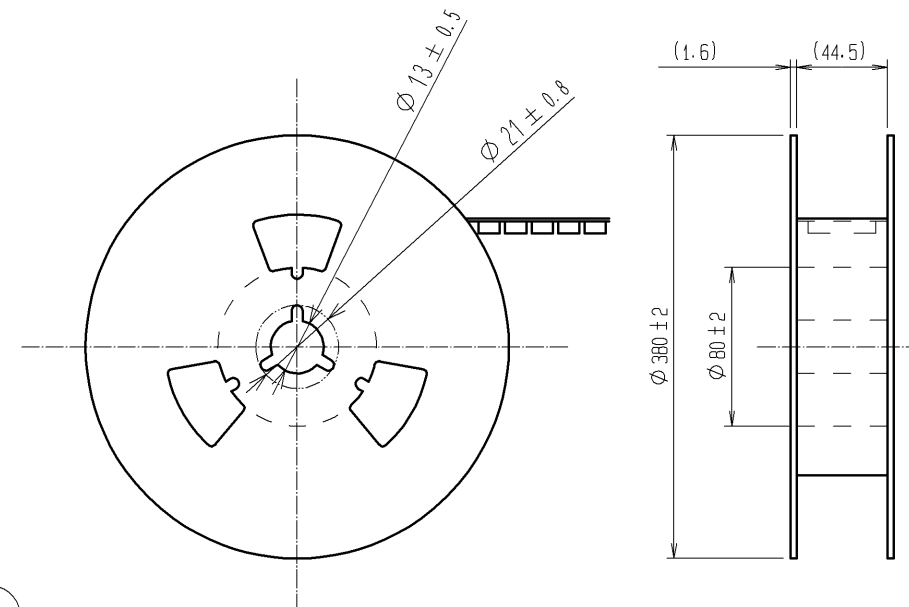
3		PHOSPHOR BRONZE	CONTACT AREA : GOLD 0.1 μ m min	5	PI	(TAPE FOR VACUUM PICK UP)		
			LEAD AREA : GOLD 0.03 μ m min	5	PE	(COVER TAPE)		
			UNDER PLATING : NICKEL 1 μ m min	4	PS	(EMBOSSSED CARRIER TAPE)		
1		LCP	BLACK. UL94V-0	2	PHOSPHOR BRONZE	OVER PLATING : TIN PLATING 1 μ m min		
						UNDER PLATING : NICKEL 0.2 μ m min		
NO.		MATERIAL	FINISH , REMARKS		NO.	MATERIAL	FINISH , REMARKS	
UNITS mm			SCALE 5 : 1		COUNT	DESCRIPTION OF REVISIONS		DESIGNED
								CHECKED
								DATE
HIROSE ELECTRIC CO., LTD.			APPROVED : HS. OKAWA	11. 09. 15	DRAWING NO.	EDC3-157330-02		
			CHECED : HT. YAMAGUCHI	11. 09. 15	PART NO.	FX16-31S-0.5SV(30)		
			DESIGNED : TS. MIYAKI	11. 09. 15	CODE NO.	CL575-3402-4-30		
			DRAWN : TS. MIYAKI	11. 09. 15				

DRAWING FOR PACKING (2:1)

THE DIRECITON OF PULLING OUT



REELED DIMENSION (FREE)



HRS

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CODE NO.	CL575-3402-4-30

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